

DESCRIPTION

AM5853 is designed for battery charging controller, which features P-channel MOSFET characteristics and a 0.12V Schottky diode for reverse current blocking. Such reverse current blocking feature cut off the current when source voltage is removed, or lower than drain voltage, no matter the gate voltage indicating the P-MOSFET on or off.

AM5853 is also suitable for high side switch in a system with multi power supplies, when isolating different power supplies becomes essential.

AM5853 can block reverse voltage as high as 10V. So it is safe enough for mobile phone system or other portable device powered by 1 cell Li-ion battery.

AM5853 make itself the smallest package available in the world.

The AM5853 is available in DFN6 and SC70-5 packages.

ORDERING INFORMATION

Package Type	Part Number			
	J6	AM5853J6R-A		
DFN6		AM5853J6VR-A		
DEINO		AM5853J6R-B		
		AM5853J6VR-B		
CC70 F	C5	AM5853C5R		
SC70-5		AM5853C5VR		
Note	V: Halogen free Package			
Note	R: Tape & Reel			
AiT provides all RoHS products				
Suffix " V " means Halogen free Package				

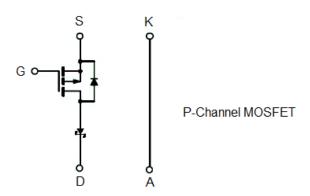
FEATURES

- PMOSFET with SBD for reverse current blocking
- 0.12V Schottky diode forward voltage
- Range of operation input voltage: Max 12V
- Charging current up to 650mA
- Environment Temperature: -20°C ~85°C
- Available in DFN6 and SC70-5 Packages

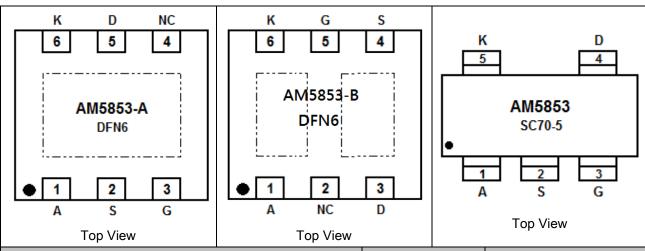
APPLICATION

Cell phone and other portable device

TYPICAL APPLICATION



PIN DESCRIPTION



	Pin#				
DFN6-A	DFN6-B		Symbol		
Single Pad	Dual Pad	SC70-5		Function	
Compatible to	Compatible to	3070-5			
DFN2x3 pin out	DFN2x2 pin out				
1	1	1	Α	Anode	
2	4	2	S	Source	
3	5	3	G	Gate	
4	2	-	NC	No Connect	
5	3	4	D	Drain	
6	6	5	К	Cathode	

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	5 sec	Steady State	Unit
Forward Voltage(Source-Drain)	V_{SD}	12		V
Gate-Source Voltage (MOSFET)	V _{GS}	-8~+0.3	-8~+0.3	V
Continuous Drain Current	l _D	0.8	0.5	Α
Pulsed Drain Current (MOSFET)	I _{DM}		1	Α
Maximum Power Dissipation	P _D	2.3	1.4	W
Operating Junction Temperature Range	TJ	-20 t	o 125	
Storage Temperature Range	T _{STG}	-40 t	o 150	°C
Soldering Recommendations (Peak Temperature)		260°0	C, 10s	

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE RATING

Parameter		Symbol	Device	Тур.	Max	Unit
			DFN6	50	60	
investiges to Amelians	t ≤ 5 sec	R _{thJA}	SC70-5	250	280	°C/W
junction-to-Ambient	Steady State		DFN6	105	120	
			SC70-5	330	400	
lumation to Casa	Standy State		DFN6	20	30	
Junction to Case	Steady State	R_{thJC}	SC70-5	150	175	

P-CHANNEL MOSFET WITH 0.12V SCHOTTKY DIODE

ELECTRICAL CHARACTERISTICS

 $T_J=25^{\circ}C$

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Threshold Voltage	V_{th}	I _{DS} =-10uA, V _{DS} =V _{GS}	-1.0	-0.7	-0.4	٧
Gate-Source Leakage current	I _{GS}	V _{GS} =8V	0	12	20	uA
PMOS off-state leakage	I _{DSS} 1	V _{GS} =0, V _S =9V, V _D =0V		0.5	5	uA
PMOS reverse block leakage	I _{DSS} 2	V _G =0, V _S =0V, V _D =4.5V		2	10	uA
On –state drain current	IDSON	Vs=5V, Vg=1V, V _D =4V	-800	-650	-500	mA
V _{DS} /I _{DSON}	RDSON	Vs=5V, Vg=1V, V _D =4V	1.25	1.5	2	Ω
Forward voltage of schottky	V _{FSBD}	Vs=4V, V _G =0V, I _{DS} =0	0.08	0.12	0.16	V

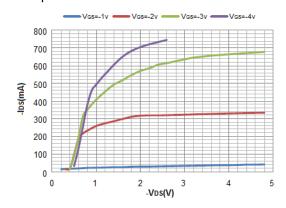


TYPICAL PERFORMANCE CHARACTERISTICS

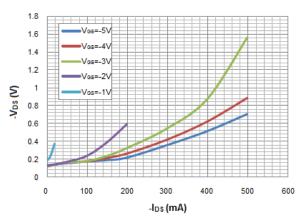
T=25°C, unless specified

T = 25°C

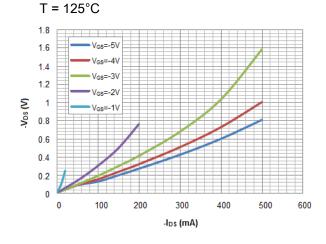
1. Output Characteristics



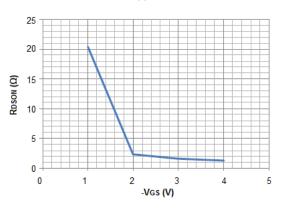
3. Dropout Voltage (V_{DS}) Vs. Charge current (I_{DS}),



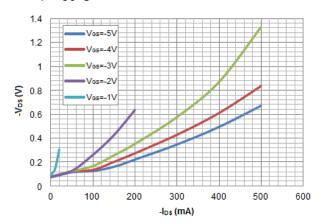
5. Dropout Voltage (V_{DS}) Vs. Charge current (I_{DS}),



2. On Resistance Vs VGS

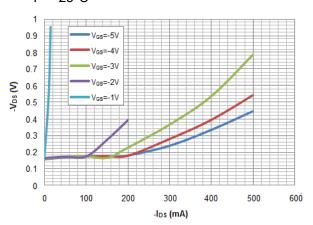


4. Dropout Voltage (V_{DS}) Vs. Charge current (I_{DS}),

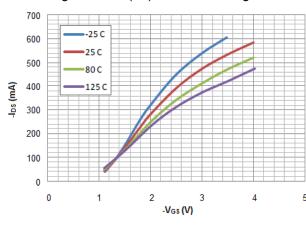


6. Dropout Voltage (V_{DS}) Vs. Charge current (I_{DS}),

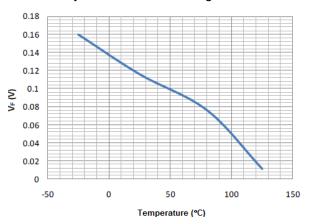
$$T = -25^{\circ}C$$



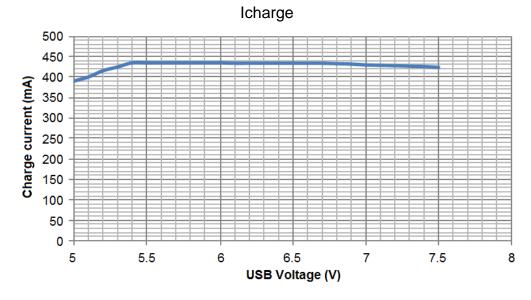
7. Charge Current (IDS) Vs. Gate Voltage



8. Schottky Diode Forward Voltage



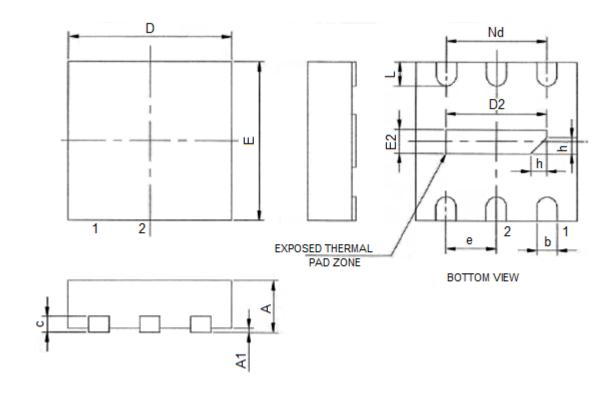
9. Charge current Vs USB voltage tested on actual cell phone powered by MTK chipset



MOSFET

PACKAGE INFORMATION

Dimension in DFN6 Single Pad (Unit: mm)

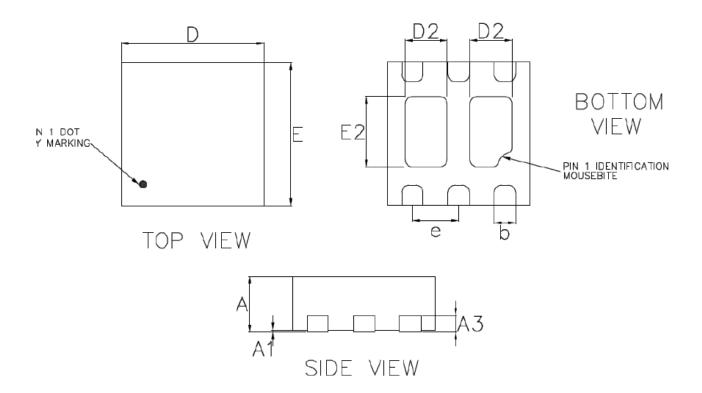


Symbol	Min	Max	
Α	0.700	0.800	
A1	-	0.050	
b	0.25	0.35	
С	0.18	0.25	
D	1.95	2.05	
D2	1.00	1.45	
е	0.65	BSC	
Nd	1.30BSC		
E	1.95	2.05	
E2	0.20	0.40	
L	0.25 0.40		
h	0.15 0.25		

MOSFET

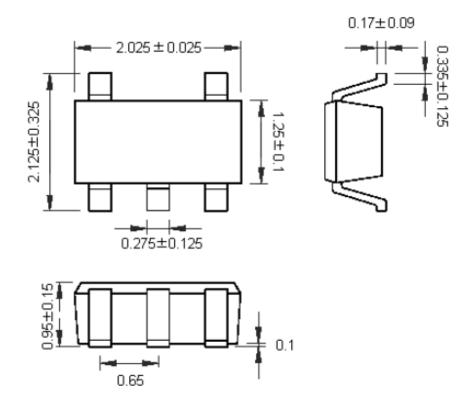


Dimension in DFN6 Dual Pad (Unit: mm)



Symbol	Min	Max	
Α	0.700	0.800	
A1	0.000	0.050	
A3	0.200	REF.	
D	1.950	2.050	
Е	1.950	2.050	
D2	0.440	0.690	
E2	0.840	1.090	
b	0.250	0.350	
L	0.175	0.375	
е	0.650 BSC.		

Dimension in SC70-5 (Unit: mm)





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